

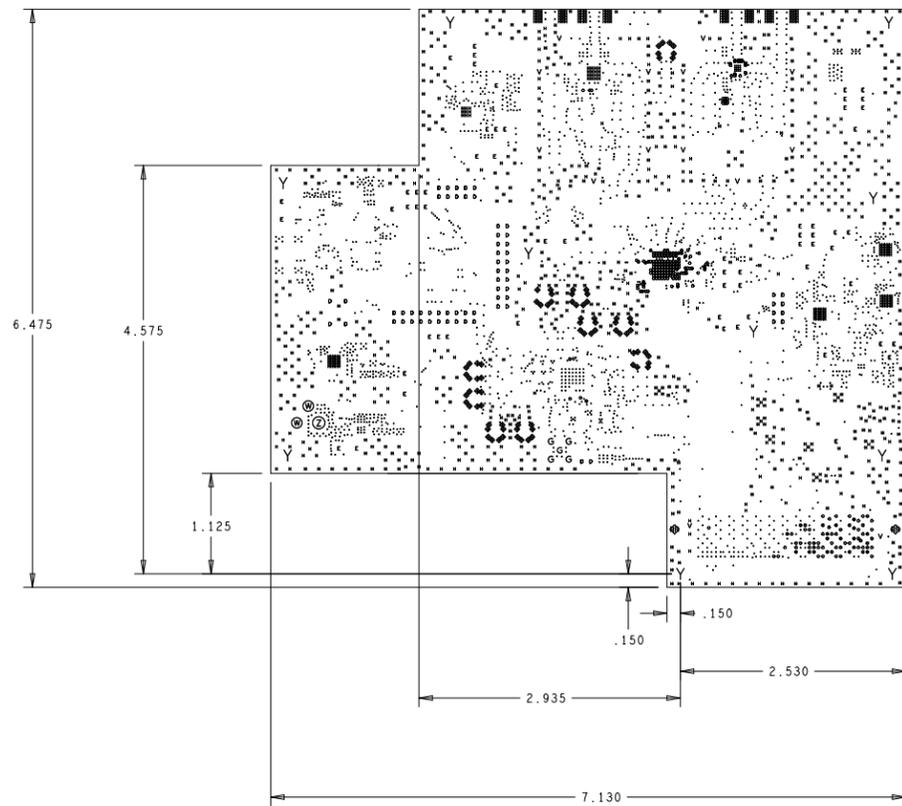
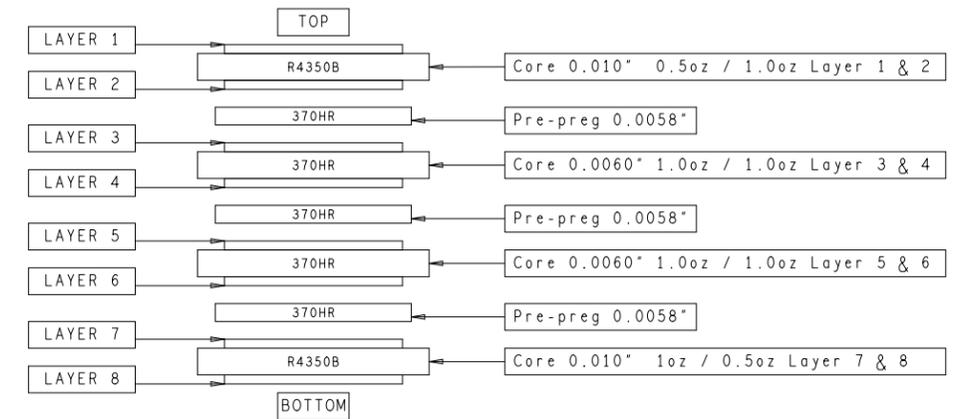
REVISIONS			
ZONE	LTR	DESCRIPTION	DATE

UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

- APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS.
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.
IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD.
IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.
- VIA 6, 8, 10 & 12MIL SIZES APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003/- .010$.
HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003$.
- REGISTRATION TOLERANCE: ARTWORK $\pm .002$.
ALL HOLE CENTERS $\pm .005$ FROM DIMENSION DATUM.
- MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.
FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
- PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.
MATERIAL: MULTI-LAYER (SEE DETAIL 'A')
SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: .062 \pm 10%
- MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
- SMOBC/IMMERSION GOLD: 2 - 8 μ IN OVER 118-236 μ IN NICKEL PLATING.
- SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT)
COLOR = RED (0.001 TO 002" THICK OVER METAL).
- SILKSCREEN BOTH SIDES USING WHITE NPI LEADFREE.
REGISTRATION TOLERANCE TO BE $\pm .005$.
INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
- P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
- BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
- BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

- ALL OUTER LAYERS USING A 20MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED \pm 10%.
- ALL OUTER LAYERS USING A 9MIL TRACE WIDTH AND 6MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL \pm 10%.
- MINIMUM COPPER CONDUCTOR WIDTH IS: 4MIL.
MINIMUM COPPER CONDUCTOR SPACING IS: 5MIL.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
- PWB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY.
MAX REFLOW OF 260 DEGREES C (6 PASSES).
- ALL THROUGH VIAS TO BE PLUGGED WITH NON-CONDUCTIVE EPOXY MATERIAL.
PLUGGED VIAS TO BE PLATED AFTER PLUGGING TO PRESENT FLAT SURFACE TO DEVICE.
NO POTHOLES.

USE VIASYSTEMS/DDI STACKUP JOB NAME: DAC38J84_R04350
THIS STACK UP DETAIL IS FOR REFERENCE ONLY



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
*	6.0	PLATED	19
*	8.0	PLATED	213
*	10.0	PLATED	2168
*	12.0	PLATED	1057
*	12.0	PLATED	4
*	15.0	PLATED	79
*	38.0	PLATED	64
*	40.0	PLATED	61
v	53.0	PLATED	12
g	62.0	PLATED	1
g	67.0	PLATED	4
⊙	106.0	PLATED	2
⊙	120.0	PLATED	2
⊙	140.0	PLATED	1
v	50.0	NON-PLATED	2
Y	125.0	NON-PLATED	10

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES \pm .XX \pm .01 \pm /- \pm .XXX \pm .005 \pm /-	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING	
MATERIAL SEE NOTE 5	DRAWN	JV SMITH	TSW38J84 EVM	
	ENG	M GUIBORD	DRAWING NO.	
FINISH SEE NOTE 7, 8, 9	SCALE		CODE IDENT NO.	REV. B
DO NOT SCALE DRAWING	SCALE NONE		SHEET 1 OF 1	